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van der Straten et al.

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## (54) ADVANCED PITCH INTERCONNECTS WITH MULTIPLE LOW ASPECT RATIO **SEGMENTS**

(71) Applicant: International Business Machines Corporation, Armonk, NY (US)

(72) Inventors: Oscar van der Straten, Guilderland Center, NY (US); Koichi Motoyama, Clifton Park, NY (US); Willie Lester Muchrison, JR., Troy, NY (US); Chih-Chao Yang, Glenmont, NY (US)

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(57)**ABSTRACT** 

A semiconductor interconnect structure and formation thereof. The semiconductor interconnect structure includes a first high aspect ratio metal line. The first high aspect ratio metal line includes a first low aspect ratio line segment and a second low aspect ratio line segment.

